

## SN74LV21A Dual 4-Input Positive-AND Gate

### 1 Features

- 2-V to 5.5-V  $V_{CC}$  Operation
- Max  $t_{pd}$  of 6 ns at 5 V
- Typical  $V_{OLP}$  (Output Ground Bounce) <0.8 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot) >2.3 V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II

### 2 Description

These dual 4-input positive-AND gates are designed for 2-V to 5.5-V  $V_{CC}$  operation.

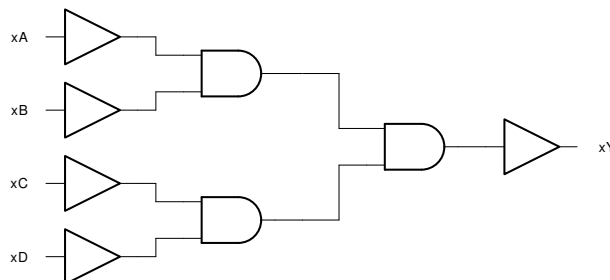
The SN74LV21A devices perform the Boolean function  $Y = A \cdot B \cdot C \cdot D$  in positive logic.

These devices are fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

#### Package Information

PART NUMBER	PACKAGE <sup>1</sup>	PACKAGE SIZE <sup>2</sup>
SN74LV21A	DGV (TVSOP, 14)	3.60 mm x 6.4 mm
	D (SOIC, 14)	8.65 mm x 6 mm
	NS (SO, 14)	10.20 mm x 7.8 mm
	DB (SSOP, 14)	6.20 mm x 7.8 mm
	PW (TSSOP, 14)	5.00 mm x 6.4 mm

- (1) For all available packages, see the orderable addendum at the end of the data sheet.
- (2) The package size (length x width) is a nominal value and includes pins, where applicable.



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## 3 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

### Changes from Revision E (April 2005) to Revision F (July 2023)

Page

- |  |          |
|--|----------|
| • Updated the numbering, formatting, tables, figures and cross-references throughout the document to reflect current data sheet standards..... | <b>1</b> |
|--|----------|

## 4 Pin Configuration and Functions

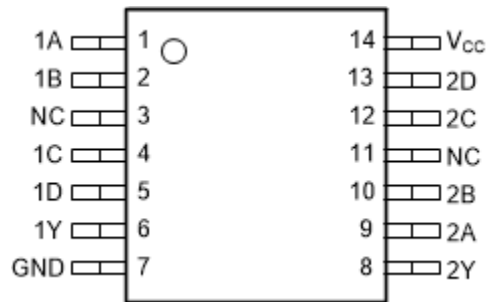


Figure 4-1. SN74LV21A D, DB, DGV, NS, or PW Package (Top View)

Table 4-1. Pin Functions

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
1A	1	I	1A Input
1B	2	I	1B Input
NC	3	—	Not internally connected
1C	4	I	1C Input
1D	5	I	1D Input
1Y	6	O	1Y Output
2Y	8	O	2Y Output
2A	9	I	2A Input
2B	10	I	2B Input
NC	11	—	Not internally connected
2C	12	I	2C Input
2D	13	I	2D Input
GND	7	—	Ground Pin
V <sub>CC</sub>	14	—	Power Pin

(1) Signal Types: I = Input, O = Output.

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	7	V
V <sub>I</sub>	Input voltage range <sup>(2)</sup>	-0.5	7	V
V <sub>O</sub>	Output voltage range applied in high or low state <sup>(2) (3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
V <sub>O</sub>	Output voltage range applied in power-off state <sup>(2)</sup>	-0.5	7	V
I <sub>IK</sub>	Input clamp current (V <sub>I</sub> < 0)		-20	mA
I <sub>OK</sub>	Output clamp current (V <sub>O</sub> < 0)		-50	mA
I <sub>O</sub>	Continuous output current (V <sub>O</sub> = 0 to V <sub>CC</sub> )		±25	mA
	Continuous current through V <sub>CC</sub> or GND		±50	mA
T <sub>stg</sub>	Storage temperature	-65	150	°C

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 5.5 V maximum.

### 5.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	± 2000
		Charged device model (CDM), per JESD22-C101 <sup>(2)</sup>	± 1000

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	2	5.5	V
V <sub>IH</sub>	High level input voltage	V <sub>CC</sub> = 2 V	1.5	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.7	
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.7	
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.7	
V <sub>IL</sub>	Low level input voltage	V <sub>CC</sub> = 2 V	0.5	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.3	
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.3	
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.3	
V <sub>I</sub>	Input voltage	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High level output current	V <sub>CC</sub> = 2 V	-50	mA
		V <sub>CC</sub> = 2.3 V to 2.7 V	-2	
		V <sub>CC</sub> = 3 V to 3.6 V	-6	
		V <sub>CC</sub> = 4.5 V to 5.5 V	-12	

### 5.3 Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
I <sub>OL</sub>	Low level output current	V <sub>CC</sub> = 2 V	50	μA
		V <sub>CC</sub> = 2.3 V to 2.7 V	2	mA
		V <sub>CC</sub> = 3 V to 3.6 V	6	
		V <sub>CC</sub> = 4.5 V to 5.5 V	12	
Δt/Δv	Input transition rise and fall rate	V <sub>CC</sub> = 2.3 V to 2.7 V	200	ns/V
		V <sub>CC</sub> = 3 V to 3.6 V	100	
		V <sub>CC</sub> = 4.5 V to 5.5 V	20	
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#)

### 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SN74LV21A					UNIT
	D	DB	DGV	NS	PW	
	14 PINS	14 PINS	14 PINS	14 PINS	14 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance					°C/W
	86	96	127	76	113	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report ([SPRA953](#)).

### 5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP	MAX	UNIT
V <sub>OH</sub>	High-level output voltage	I <sub>OH</sub> = -50 μA	2 V to 5.5 V	V <sub>CC</sub> - 0.1		V
		I <sub>OH</sub> = -2 mA	2.3 V	2		
		I <sub>OH</sub> = -6 mA	3 V	2.48		
		I <sub>OH</sub> = -12 mA	4.5 V	3.8		
V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> = 50 μA	2 V to 5.5 V	0.1		V
		I <sub>OL</sub> = 2 mA	2.3 V	0.4		
		I <sub>OL</sub> = 6 mA	3 V	0.44		
		I <sub>OL</sub> = 12 mA	4.5 V	0.55		
I <sub>I</sub>	Input leakage current	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V	±1		μA
I <sub>CC</sub>	Supply current	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V	20		μA
I <sub>off</sub>	Off-state leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5 V	0 V	5		μA
C <sub>i</sub>	Input capacitance	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	1.9		pF

### 5.6 Switching Characteristics, V<sub>CC</sub> = 2.5 V ± 0.2 V

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			SN74LV21A		UNIT
				MIN	TYP	MAX	MIN	MAX	
t <sub>pd</sub>	A, B, C or D	Y	C <sub>L</sub> = 15 pF		7	12	1	14	ns
t <sub>pd</sub>	A, B, C or D	Y	C <sub>L</sub> = 50 pF		9.2	15.7	1	19	

### 5.7 Switching Characteristics, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#) )

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN74LV21A		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A, B, C, or D	Y	$C_L = 15\text{ pF}$		5.1	7	1	8.5	ns
$t_{pd}$	A, B, C, or D	Y	$C_L = 50\text{ pF}$		6.6	10.5	1	12	

### 5.8 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#) )

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN74LV21A		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A, B, C, or D	Y	$C_L = 15\text{ pF}$		3.8	5	1	6	ns
$t_{pd}$	A, B, C, or D	Y	$C_L = 50\text{ pF}$		4.9	7	1	8	

### 5.9 Noise Characteristics

$V_{CC} = 3.3\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER <sup>(1)</sup>		MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic $V_{OL}$		0.2	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic $V_{OL}$		0	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic $V_{OH}$		3.2		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

(1) Characteristics are for surface-mount packages only.

### 5.10 Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		$V_{CC}$	TYP	UNIT
$C_{pd}$	Power dissipation capacitance	$C_L = 50\text{ pF}$ ,	$f = 10\text{ MHz}$	3.3 V	17.4	pF
				5 V	20.2	

## 6 Parameter Measurement Information

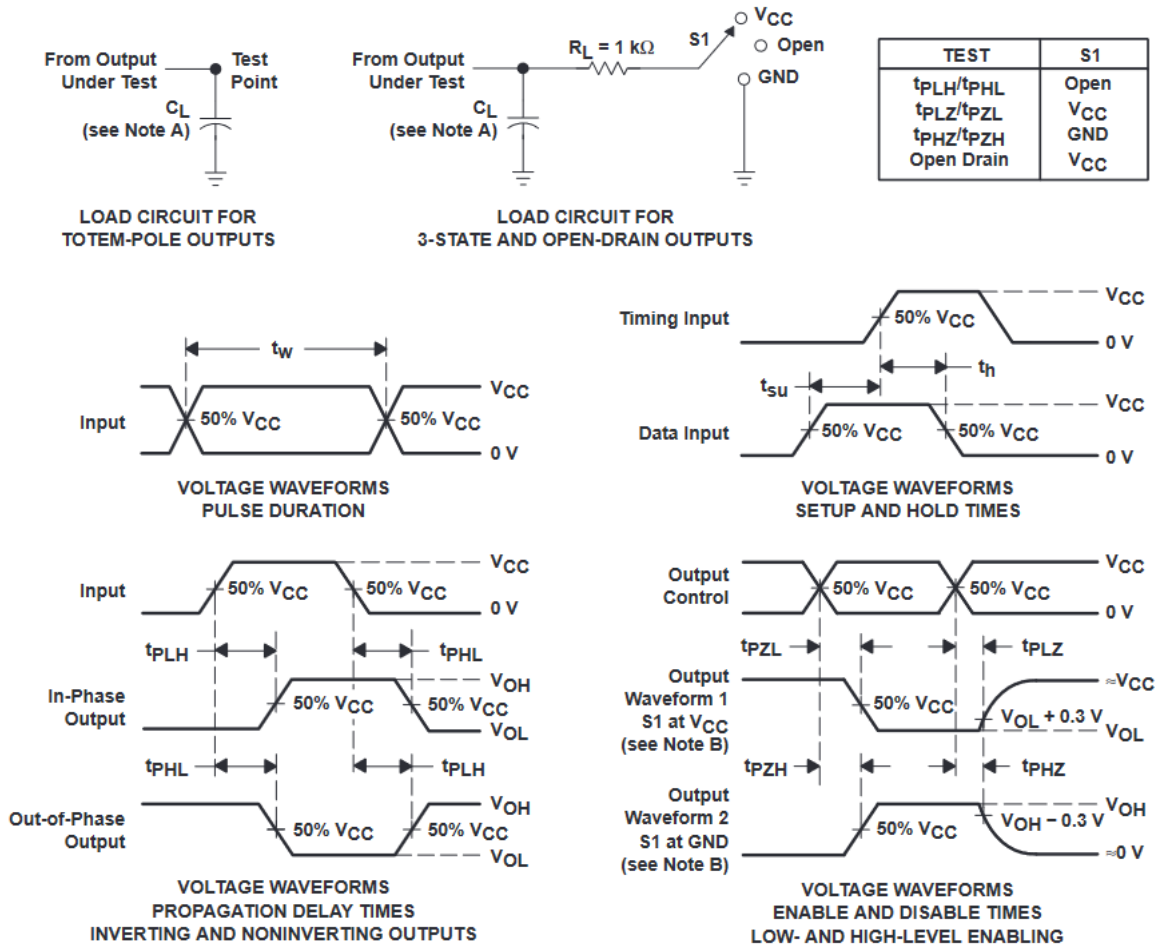


Figure 6-1. Load Circuit and Voltage Waveforms

- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 3$  ns,  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

## 7 Detailed Description

### 7.1 Overview

These devices are fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The SN74LV21A devices perform the Boolean function  $Y = A \cdot B \cdot C \cdot D$  in positive logic. These dual 4-input positive-AND gates are designed for 2-V to 5.5-V  $V_{CC}$  operation.

### 7.2 Functional Block Diagram

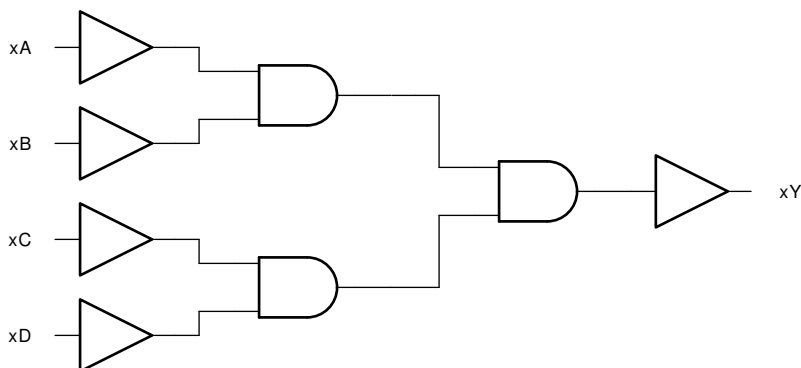


Figure 7-1. logic diagram (positive logic)

### 7.3 Device Functional Modes

Function Table  
(each gate)

INPUTS <sup>(1)</sup>				OUTPUT <sup>(2)</sup>
A	B	C	D	Y
H	H	H	H	H
L	X	X	X	L
X	L	X	X	L
X	X	L	X	L
X	X	X	L	L

(1) H = High Voltage Level, L = Low Voltage Level, X = Do not Care, Z = High Impedance

(2) H = Driving High, L = Driving Low, Z = High Impedance State

## 8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 8.1 Documentation Support (Analog)

#### 8.1.1 Related Documentation

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74LV21A	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 8.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
All trademarks are the property of their respective owners.

### 8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74LV21AD</a>	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-40 to 85	LV21A
<a href="#">SN74LV21ADBR</a>	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A
SN74LV21ADBR.A	Active	Production	SSOP (DB)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A
<a href="#">SN74LV21ADGVR</a>	NRND	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A
SN74LV21ADGVR.A	NRND	Production	TVSOP (DGV)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A
<a href="#">SN74LV21ADR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	LV21A
SN74LV21ADR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A
<a href="#">SN74LV21ANSR</a>	NRND	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV21A
SN74LV21ANSR.A	NRND	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV21A
<a href="#">SN74LV21APW</a>	Obsolete	Production	TSSOP (PW)   14	-	-	Call TI	Call TI	-40 to 85	LV21A
<a href="#">SN74LV21APWR</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	LV21A
SN74LV21APWR.A	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A
SN74LV21APWRG4	Active	Production	TSSOP (PW)   14	2000   null	No	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A
SN74LV21APWRG4	Active	Production	TSSOP (PW)   14	2000   null	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A
SN74LV21APWRG4.A	Active	Production	TSSOP (PW)   14	2000   null	No	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A
SN74LV21APWRG4.A	Active	Production	TSSOP (PW)   14	2000   null	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV21A

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

**(6) Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

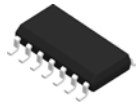
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV21ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV21ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV21ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV21ANSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LV21APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV21ADBR	SSOP	DB	14	2000	353.0	353.0	32.0
SN74LV21ADGVR	TVSOP	DGV	14	2000	353.0	353.0	32.0
SN74LV21ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LV21ANSR	SOP	NS	14	2000	353.0	353.0	32.0
SN74LV21APWR	TSSOP	PW	14	2000	353.0	353.0	32.0

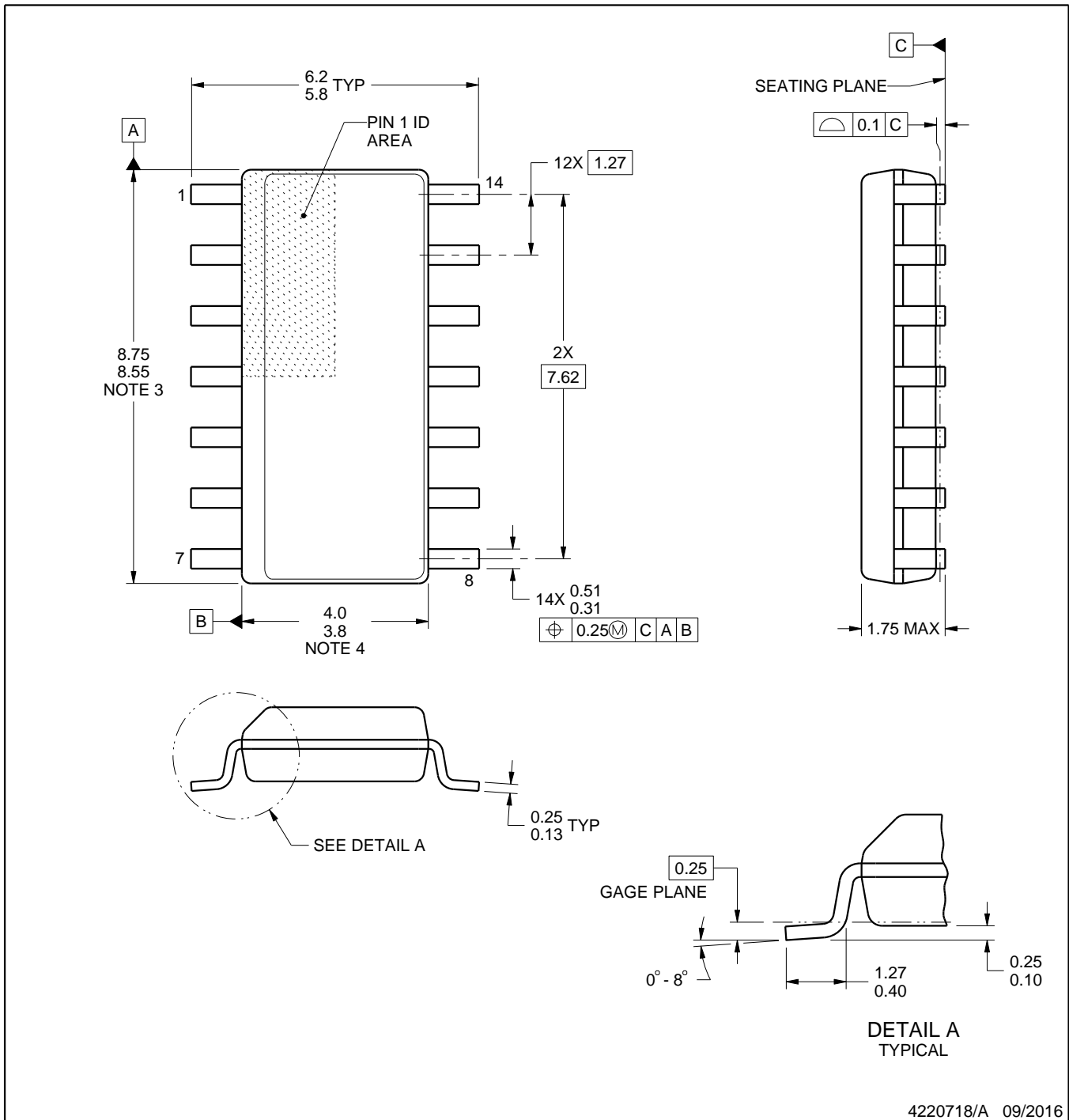
D0014A



# PACKAGE OUTLINE

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

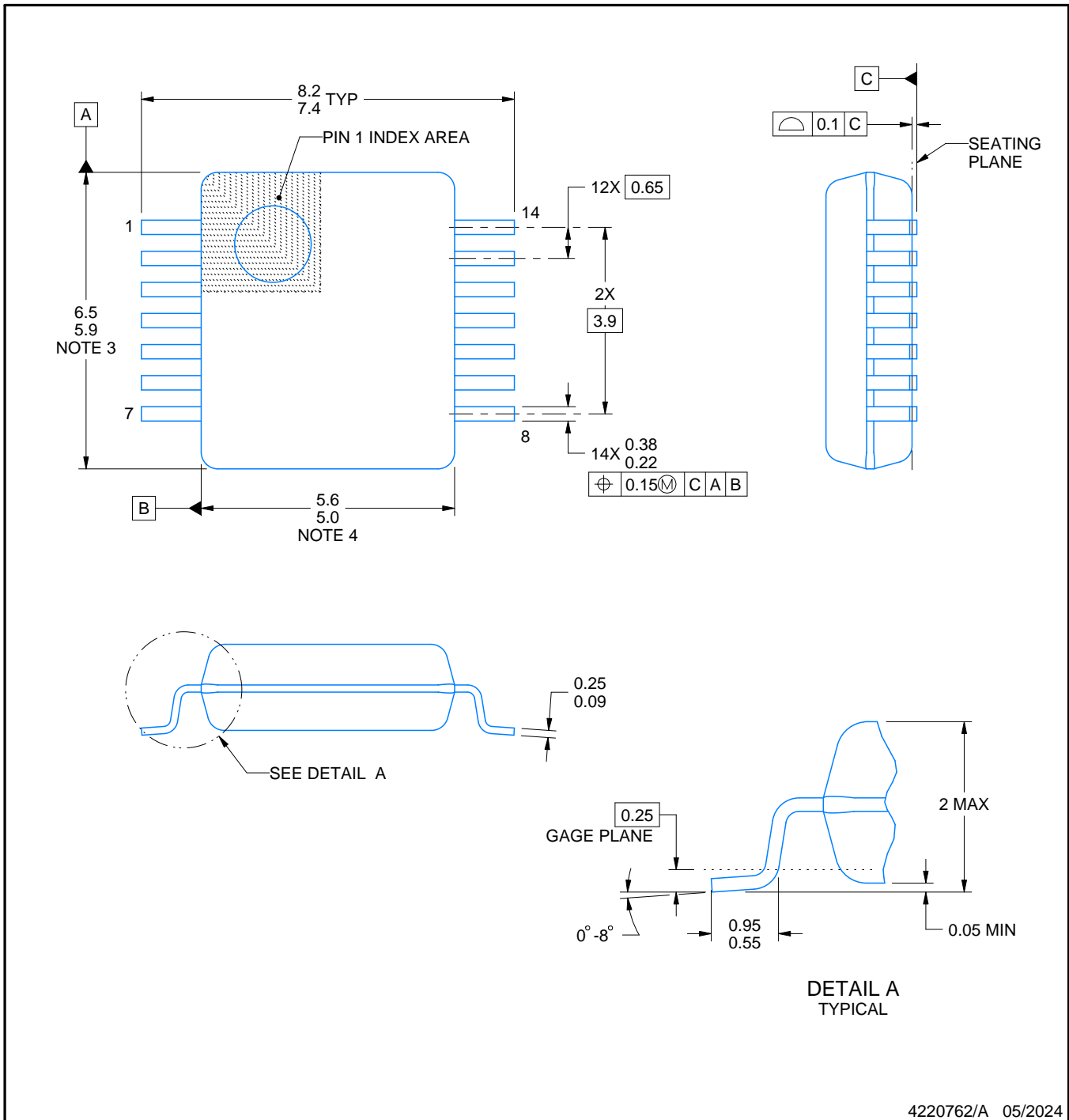
# DB0014A



# PACKAGE OUTLINE

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



**NOTES:**

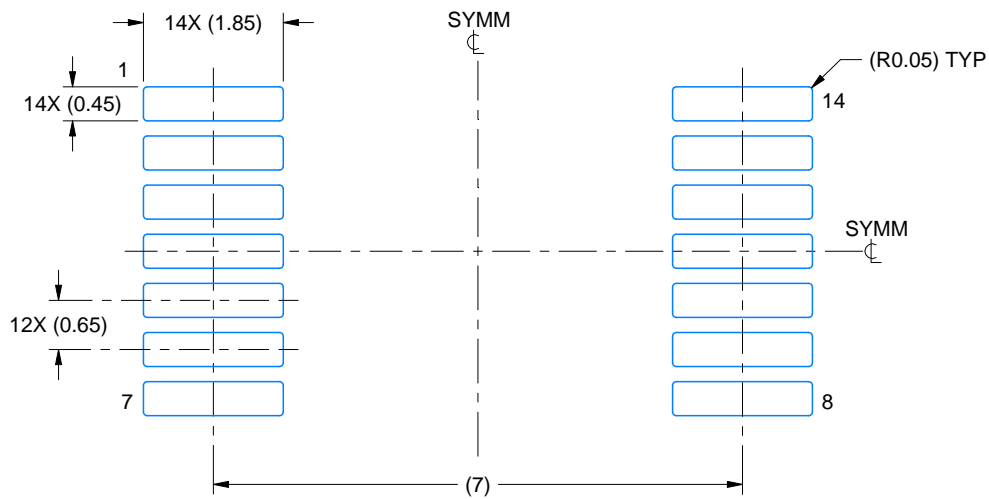
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

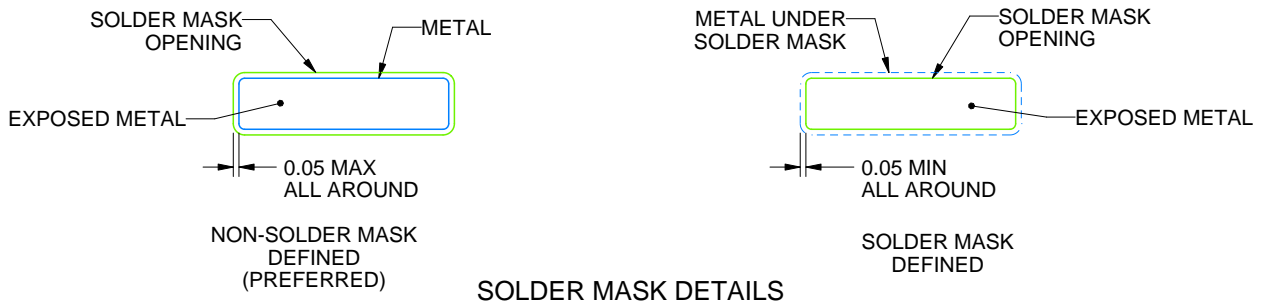
DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220762/A 05/2024

NOTES: (continued)

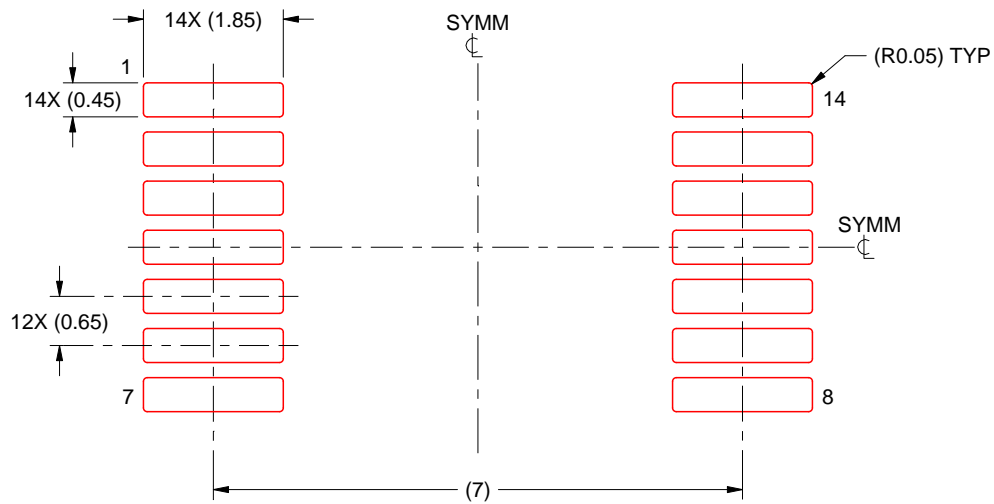
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.



4220202/B 12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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